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REMARKS

After the foregoing amendment, claims 8-10, 13-15 and 36 are active in the present application. Claims 1-7 and 11-12 have been cancelled, claims 8, 14 and 36 amended, and claims 16-35 previously were withdrawn. No new matter has been added by the amendment and the amendment is believed to place the application in condition for allowance. Accordingly, reconsideration and allowance of the application are respectfully requested.

Independent claims 8 and 14 were rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 6,211,462 (Carter) or 6,376,905 (Hisano). Independent claim 36 was rejected under 35 U.S.C. §102(e) as being anticipated by U.S. Patent No. 6,396,103 (Crowley). Applicants respectfully traverse the rejections.

The present invention is directed to packaged semiconductor device having a dual gauge leadframe. The leadframe has a first leadframe portion including leads that is a first thickness of about 8 mils, and a second leadframe portion including a die paddle for receiving an integrated circuit (IC), the second portion having a second thickness of about 20 mils.

Independent claims 8, 14 and 36 each have been amended to recite that the die is attached to the die paddle (i.e., the second leadframe portion) using a high temperature die attach process and the wires are wire bonded to the leads (i.e., the first lead frame portion) using a low temperature wirebonding process. This amendment is supported in the specification at, for example, paragraph [0013] on page 4. Claims 8, 14 and 36 also have been amended to recite that the first leadframe portion has a thickness of about 8 mils and the second leadframe

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portion has a thickness of about 20 mils, which is supported at page 7, the latter part of paragraph [0026] of the specification.

None of the cited references disclose the specific dimensions of the first and second leadframe portions now recited in the claims and thus the claims are not anticipated by the cited references. Accordingly, Applicants respectfully request that the rejections under 35 U.S.C. §102 be withdrawn.

Claims 3, 7 and 12, which related to the relative thicknesses of the first and second leadframe portions were rejected under 35 U.S.C. §103 as unpatentable over Hisano and the remark that the relative and specific thicknesses of the first and second leadframe portions are considered obvious since a person skilled in the art would have been motivated to find the optimum value using routine design skill and the teachings of Hisano. Applicants respectfully traverse the rejection as it applies to the amended claims.

Hisano FIG. 1 shows the leads 6 being thicker than the tab 3 to which a chip 1 is attached. FIGS. 2-5 show the tab 3 and leads 6 being of the same thickness. Only FIG. 6 shows the tab 13 being thicker than the leads 6. However, the specification only says that the tab 13 is formed thicker than the leads, but no teachings of any specific thicknesses or thickness ranges is provided and the drawing scale is about 1:10 (leads to tab). Crowley teaches a difference of nearly 1:5 (see Crowley, col. 5, lines 20-25), whereas Carter, whose aim is to minimize the distance between lead tips and chip bond pads, is closer to 1:1. In contrast, the present invention uses relative thicknesses of about 1:2, which allows for easy singulation during assembly and good heat dissipation when the package is used.

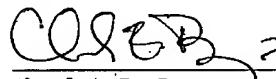
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Accordingly, in view of the foregoing amendment and remarks, Applicants respectfully submit that the present application, including claims 8-10, 13-15 and 36, is in condition for allowance and such action is respectfully solicited.

Respectfully submitted,

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